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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AMENDMENT "C" AFTER FINAL

APPLICANTS: Yuji Takaoka et al. ATTY DOCKET NO: 09792909-4794
SERIAL NO.: 09/816,055 GROUP ART UNIT: 2813
DATE FILED: March 23, 2001 EXAMINER: Nema Berezny
INVENTION: "SEMICONDUCTOR DEVICE HAVING A PLURALITY OF
ENCUSTED SEMICONDUCTOR CHIPS (As Amended)"

Hon. Assistant Commissioner for Patents
Washington, DC 20231

S I R:

This Amendment "C" After Final is filed in response to the Final Office Action of November 4, 2002. Please reconsider the application in view of the amendment and remarks presented below.

IN THE CLAIMS

Please amend claims 1 and 7 as follows:

B¹
1. (Twice Amended) A semiconductor device, comprising:
a plurality of semiconductor chips mounted on an outer surface of a substrate;
a single-layer insulation film provided on said substrate, wherein a top surface and side surfaces of said plurality of semiconductor chips are encrusted in said insulation film; and
wiring provided on said insulation film, wherein said wiring is connected to said plurality of semiconductor chips through a connection hole formed on said insulation film.

B²
7. (Twice Amended) A semiconductor device, comprising:
a plurality of semiconductor chips;
a single-layer insulation layer supporting said plurality of semiconductor chips, wherein a top surface and at least a portion of side surfaces of said plurality of semiconductor chips are encrusted in said insulation layer and a surface opposite said top surface of said plurality of semiconductor chips is exposed; and
wiring provided on said insulation layer, wherein said wiring is connected to each semiconductor chip of said plurality of semiconductor chips through a connection hole formed on said insulation layer.

Please cancel claims 13-16.



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IN RE APPLICATION OF: Yuji Takaoka, et al. ATTORNEY DOCKET NO. 09792909-4794
SERIAL NO.: 09/816,055 GROUP ART UNIT: 2813
FILED: March 23, 2001 EXAMINER: N. Berezny
FOR: "SEMICONDUCTOR DEVICE HAVING A PLURALITY OF ENCRUSTED SEMICONDUCTOR CHIPS (AS AMENDED)"

AMENDMENT "C" AFTER FINAL

Hon. Assistant Commissioner of Patents
Washington D.C. 2023
SIR:

Transmitted herewith is an amendment in the above-identified application.

☒ No additional claim fee is required.

The fee has been calculated as shown below.

CLAIMS AS AMENDED						
	(2) CLAIMS REMAINING AFTER AMENDMENT		(4) HIGHEST NO. PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEE
TOTAL CLAIMS		MINUS			() X 9.00 (X) X 18.00	0.00
INDEP. CLAIMS		MINUS			() X 42.00 (X) X 84.00	0.00
Application amended to contain any multiple dependent claims not previously paid for.				() YES () NO	() \$140.00 () \$280.00 ONE TIME	
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00	

* If the entry in Column 2 is less than the entry in Column 4, write "0" in Column 5
** If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20 write "20" in this space.

- ☐ Applicant petitions the Commissioner of Patents and Trademarks to extend this time for response to the Office Action dated _____ for _____ month(s) so that the period for response is extended to ____.
- ☐ The Commissioner is requested and authorized to charge the amount of \$____ for the extension fee to American Express Account No. 378571697401002 to cover the required fee. Form 2038 is attached for that purpose.
- ☐ A check for \$____ accompanying attached Terminal Disclaimer under 37 C.F.R. §1.321.
- ☐ A check for \$____ and Petition
- ☒ The Commissioner is hereby authorized to any additional fees which may be required, or to credit any overpayment to account No. 19-3140. A duplicate of this sheet is enclosed.
- When phoning re this application, please call 312/876-8000 - Ext. 2606.

SONNENSCHNEN NATH & ROSENTHAL

BY Christopher P. Rauch (Reg. No. 45,034)
Christopher P. Rauch

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Assistant Commissioner of Patents, Washington, D.C. 20231 on February 4, 2003

Christopher P. Rauch
SIGNATURE
February 4, 2003